

A

B

C

D

A

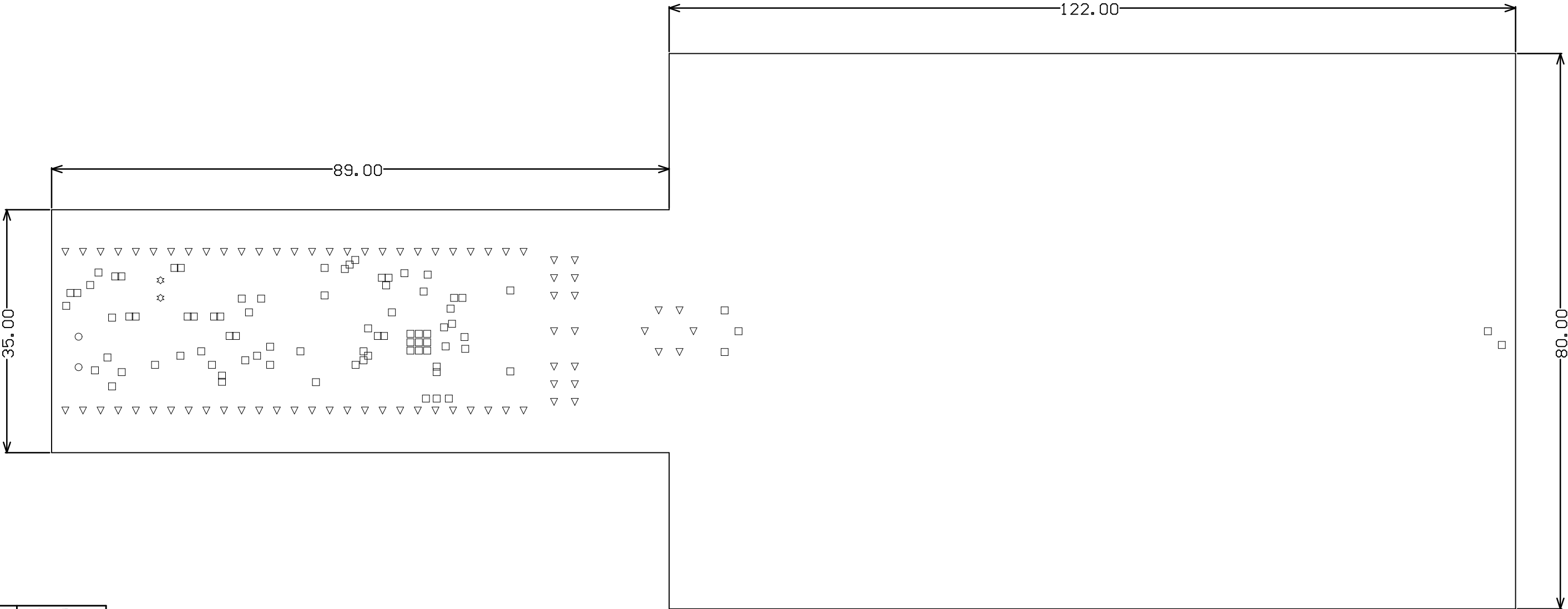
B

C

D

- Master Drawings:
- material: FR4, Tg: 150
  - thickness: 1.55mm
  - layer stackup: - Top Cu: 35um
    - Bottom Cu: 35um
  - min. hole metalization: 20um
  - surface finishing: ENIG
  
  - solder mask: - in accordance with IPC-SM-840
    - Liquid Photo Imageable (LPI)
    - color: BLUE
    - unless otherwise defined (in gerber), solder mask overlap on SMT pads is not allowed

- bow and twist: - max. 0.75% SMT boards
  - max. 1.5% THT boards
- point of origin (0,0): bottom left corner
- board is designed on 0.050 mm grid
- primary side: Top layer



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	85	0.3mm (11.81mil)	PTH	Round
▽	74	0.9mm (35.433mil)	PTH	Round
○	2	0.9mm (35.433mil)	NPTH	Round
☆	2	1.016mm (40mil)	PTH	Round
163 Total				

Title: *CLEV663B\_ Blueboard*

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